



GT-70

Extremely Soft and Elastic Graphene Enhanced Thermal Interface Material

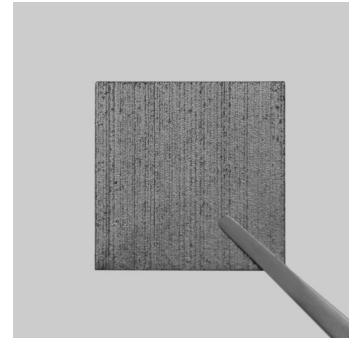
Part No: GT7004A-400400

Features:

- Very High Thermal Conductivity
- Very Low Effective Thermal Resistance
- High Compressibility and Ultra Light

Applications:

IGBT,GPU,CPU,LED,RF Module, 5G devices, Opto and power module cooling



Description:

GT-70 is a highly soft graphene enhanced thermal interface material. It has very low effective thermal resistance (11 kmm²/W at 275Kpa). Moreover, the GT-70 has advantages of low density, low complexity during assembly and good maintainability. GT-70 opens new opportunities for addressing large heat dissipation issues in electronics and other high power driven systems.

Physical Properties	Value	Units	Test Method
Thermal Conductivity	70 ± 5	W/mK	ASTM5470
	400±50	W/mK	LFA447
Thermal Resistance	11 ± 0.5 (275KPa, 300µm)	Kmm ² /W	ASTM5470
Thickness Range for Production	0.3-1*	mm	Micrometer
Thickness Range for Prototype	0.250**	mm	Micrometer
Thickness Tolerance	3	%	Micrometer
Pad Size	Up to 55*55	mm ²	-
Compressibility	>50	%	-
Compressive Strength	550±100 (300µm)	kPa	At 50% compression
Recovery	>70	%	-
Tensile strength	50±20	kPa	Tensile tester
Surface Roughness (Ra)	5±3	µm	Wyko NT1100 optical profilometer
Surface Roughness (Rz)	30±15	µm	Wyko NT1100 optical profilometer
Application Temperature	-40 to 200	°C	-
Flammability	V-0		UL94
Specific Heat	0.2-0.3	J/g.K	Hotdisk
Density	0.30±0.05	g/cm ³	Balance and Micrometer
Color	Grey	-	Visual

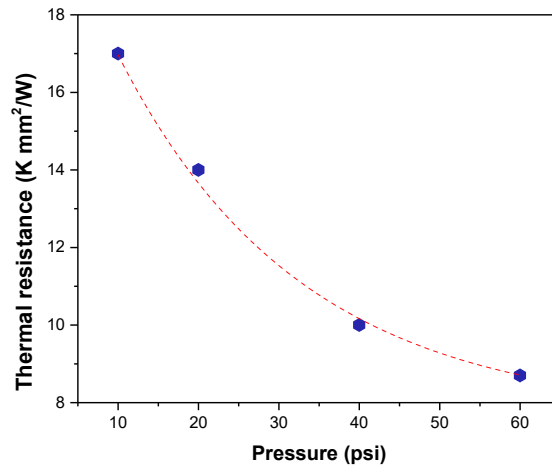
Notes:

* Quality is guaranteed for production

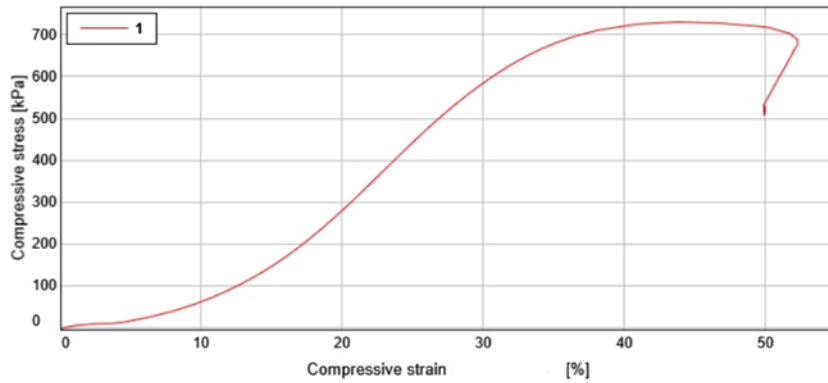
** This thickness of the current prototype samples .

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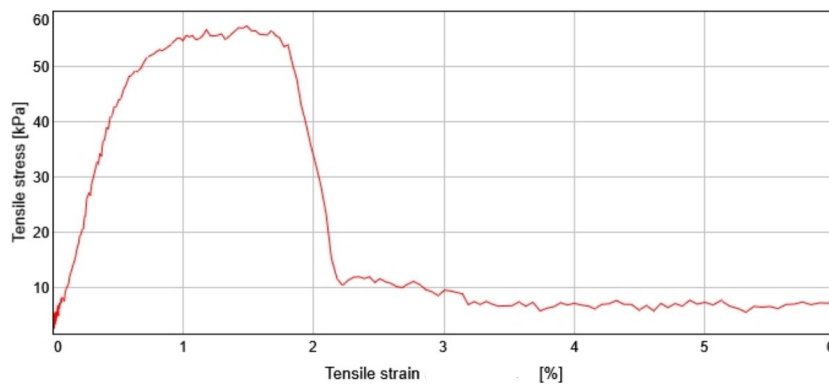
Thermal Resistance vs Pressure (300µm)



Compressive Stress vs Strain Curve at 50% compression (300µm)



Tensile Strength



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